



Feasibility of integrated single-stage 48V to 1V conversion using GaN power devices

Minxiang Gong Arijit Raychowdhury

Industry Advisory Board (IAB) November 2019



Georgia Tech



Research Centers

Liaisons

Georgia 1. Introduction



Conventional board net: 12V

Board net at its power limit
High wiring costs: >70 kg, >2.5 km

Introduction of 48V board net:

- Enable new high-power applications
- More power/better efficiency, CO₂ reduction

Conventional power distribution: 12V

- High current/wiring cost
- Up to 10 PSU close to server blades

Introduction of 48V power distribution:

- Lower transmission loss
- 1 central PSU





A Integrated 48V to 1V single-stage DC-DC regulator for point-of-load:

- High efficiency (>90%), high output current (10A)
- Integrated with load chip in same package

2. Target

Georgia

Tech





Georgia 4. Topology



Linear regulator:

Cons:

□ simple

no switching noise

Iow ripple

Pros:

VIN

 \Box η = Vout/Vin

Error amp



VIN

Vo

Switching regulators:

Cons:

- High efficiency at high input voltage
- Passive scales with frequency Pros:
- Hard to integrate large passives
- High ripple
- Low efficiency at light load current



Industry Advisory Board (IAB) November 2019

Ge	eorgia Tech	5. Silicon vs GaN		PRC Confidential	rgia Tech
		Body + Source Gate Drain P+ N+ P Well EFF N Well P+ Sub	Source/Body N+ P+ Pbody N _{drift} N-HEI or NBL N+ substrate Drain		
		Si – Lateral	Si – Vertical	GaN	
	Switch	Fully integrated	External	External	
	I _{out}	<5A	>5A	>5A	
	Q _G ⋅R _{DSon}	Low 2-	5x Medium 2	-4x High	
	Q _{oss} ·R _{DSon}	Low 1	0x Medium 1	5x High	
	Area · R _{DSon}	Low 3	X Medium <u>1</u>	<mark>5x</mark> High	
	dV _{sw} /dt	<50V/ns		Up to 500V/ns	
Comparison between silicon and GaN power devices					
Industry Advisory Board (IAB)					

November 2019

Georgia 6. System architecture 6.1 Slide Subtitle



Synchronous buck converter with GaN power devices:

- Low voltage PWM controller: voltage regulate and dead time control
- Level shifter: signal voltage level changing
- Bootstrap circuit: high side GaN device drive
- Gate driver: provide enough drive strength for large GaN device





Georgia Tech



7. Loss analysis

7.1 Slide Subtitle



Main losses:

- **Conduction** loss
- Switching loss in MOSFET
- Reverse recovery loss of diode
- Dead time loss

- Output capacitor loss in MOSFET
- **Gate charge** loss
- Inductor conduction loss
- Capacitor loss

Industry Advisory Board (IAB) November 2019



Georgia 8. Challenges 8.1 Dead time control

Dead time related losses:

- Dead time too long: reverse recovery loss and body diode conduction loss
- Dead time too short: non zero-voltage switching (must avoid)
- Optimal dead time: loss eleminated



PRC Confidential

Georgia 9. Challenges 9.1 High speed level shifter



Sub-nano delay high voltage level shifter:

- High speed: dV/dt > 20V/ns
- Small delay: < 1ns</p>
- Low static power



Industry Advisory Board (IAB) November 2019

PRC Confidential



SPICE simulation results with GaN model and Verilog A

10. Results

10.1 efficiency



Industry Advisory Board (IAB) November 2019

Georgia

Tech

Georgia 11. results 11.1 level shifter and loss breakdown

Simulation results of level shifter and loss breakdown



Industry Advisory Board (IAB) November 2019

Georgia Institute of Technology



Georgia Tech

Georgia 12. Conclusion



Conclusion:

- A feasibility study of single-stage 48V to 1V conversion
- Peak efficiency can achieve 75% with proper dead time control

Next step:

- New dead time control and current voltage sensing scheme
- High speed and high reliability level shifter

Reference:

- [1] Wittman, JSSC16
- **[2]** Barner, APEC16
- **[3]** Aklimi, JSSC17
- **[4]** Liu, JSSC15
- □ [5] Xue, ISSCC16
- **[6] Ke**, ISSCC16
- [7] Seo, ECCE18

- □ [8] Das, APEC19
- [9] Rentmeister, APEC17
- □ [10] TI, PMP4497
- □ [11] TI, PMP4486
- □ [12] ViCOr, PI3523-00-LGIZ
- □ [1<mark>3] ViCOr, PI354</mark>2-00-xGIZ